

## FEATURES

- | Size Design  $\Phi 5.5 \times 6.0 \text{mm}$

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- | High Current Handling Capability 5,000A @ 8/20  $\mu\text{s}$

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- | Low Capacitance and Insertion Loss

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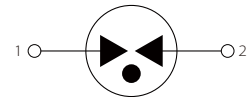
- | Quick Response and Long Service Life

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- | Moisture sensitivity level: Level 1

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 $\Phi 5.5 \times 6.0 \text{mm}$ 


Schematic Symbol

## APPLICATION INFORMATION

- | Communication equipment.

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- | Repeaters, Modems

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- | Telephone Interface, Line cards.

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- | Data communication equipment.

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## AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free

## PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

## ELECTRICAL PARAMETER

Parameter	Symbol	Limit	Unit
DC Blocking Voltage 1)	100V/s	1600-2400	V
Impulse Spark-over Voltage	At 1kV/ $\mu$ s	for 99 % of measured values $\leq$ 3500	V
	At 1kV/ $\mu$ s	Typical values of distribution $\leq$ 3000	V
Impulse Discharge Current 2)	8/20 $\mu$ s $\pm$ 5times	5	KA
Insulation Resistance	DC=100V	$\geq$ 1	G $\Omega$
Capacitance at 1MHz	V <sub>DC</sub> =0.5V	$\leq$ 1	pF
Operating and Storage Temperature		-40~125	$^{\circ}$ C

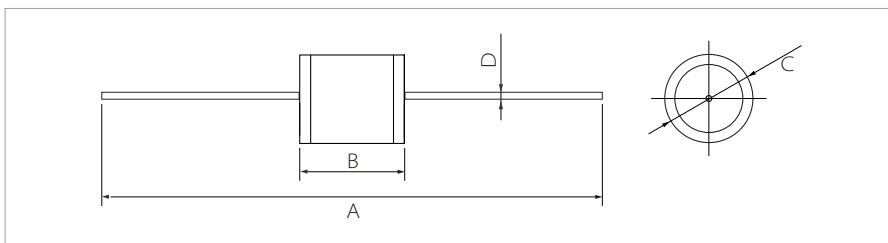
1) In ionized mode

3) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

## ENVIRONMENTAL RELIABILITY CHARACTERISTICS

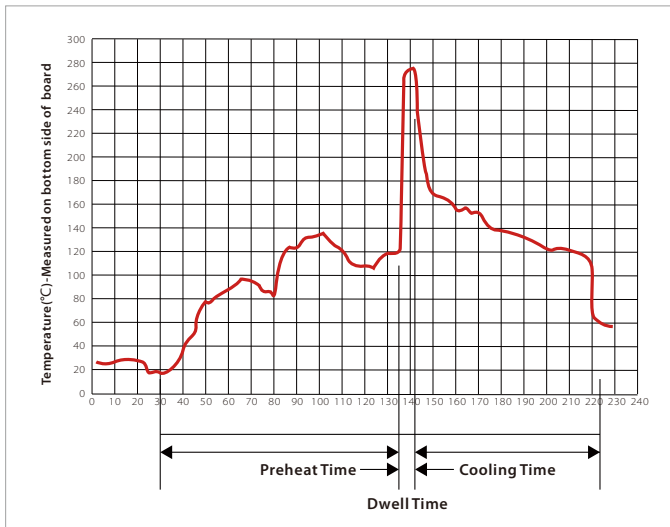
Testing items	Technical standards
High Temperature Storage Test	Temperature: 125 $^{\circ}$ C ; Time:2H
Low Temperature Storage Test	Temperature: -40 $^{\circ}$ C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude: 0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260 $\pm$ 5 $^{\circ}$ C; Time of dip soldering: 10s,1time

## PRODUCT DIMENSIONS



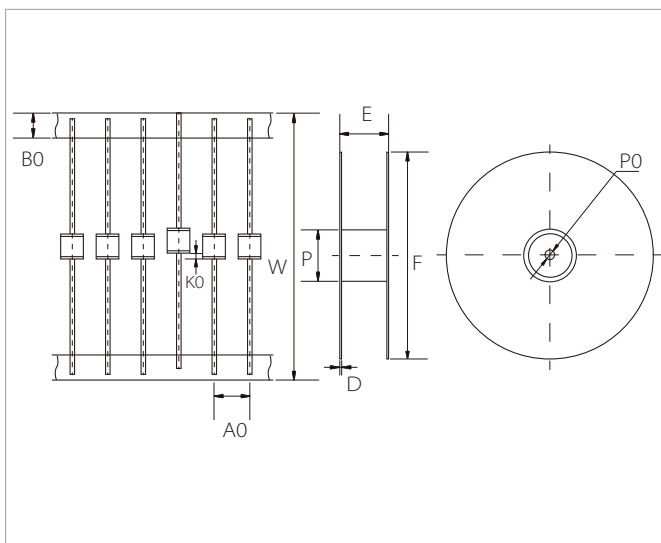
Ref.	Outline Dimensions
	Millimeters
A	62 $\pm$ 2
B	6 $\pm$ 0.2
C	$\Phi$ 5.5 $\pm$ 0.2
D	$\Phi$ 0.8

## WAVE SOLDERING




Wave Parameter		Lead-free assembly
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time(min to max)	60 – 180 secs
Solder pot Temperature		280°C Max
Solder Dwell Time		2-5 seconds

## TAPE AND REEL SPECIFICATION



Ref.	Dimensions	
	Millimeters	Inches
W	65±2	2.559±0.079
A0	10±0.5	0.394±0.020
B0	6±1	0.236±0.012
K0	1.2 Max.	0.47 Max.
D	2.5±0.5	0.098±0.020
F	340±2	13.39±0.079
E	73±2	2.874±0.079
P	82±2	3.228±0.079
P0	Φ16±1	Φ0.63±0.039

## ORDERING INFORMATION

Part Number	Size	Marking	Qty/pcs	
			Reel	Carton
SG2R05B2000	Φ5.5*6.0mm	 SG2000 05	1000	4000

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